

# DATA SHEET

**BFT92W**

PNP 4 GHz wideband transistor

Product specification

May 1994



# PNP 4 GHz wideband transistor

# BFT92W

### FEATURES

- High power gain
- Gold metallization ensures excellent reliability
- SOT323 (S-mini) package.

### APPLICATION

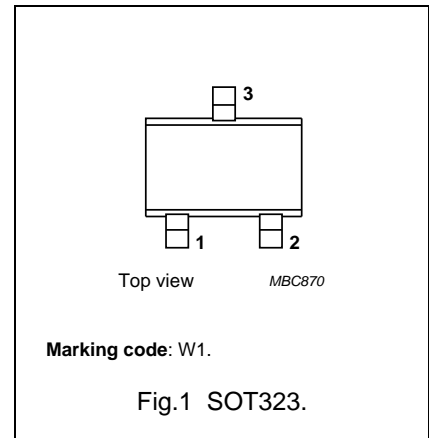
It is intended as a general purpose transistor for wideband applications up to 2 GHz.

### DESCRIPTION

Silicon PNP transistor in a plastic, SOT323 (S-mini) package. The BFT92W uses the same crystal as the SOT23 version, BFT92.

### PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



### QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{CBO}$	collector-base voltage	open emitter	–	–	–20	V
$V_{CEO}$	collector-emitter voltage	open base	–	–	–15	V
$I_C$	collector current (DC)		–	–	–35	mA
$P_{tot}$	total power dissipation	up to $T_s = 93\text{ }^\circ\text{C}$ ; note 1	–	–	300	mW
$h_{FE}$	DC current gain	$I_C = -15\text{ mA}$ ; $V_{CE} = -10\text{ V}$	20	50	–	
$C_{re}$	feedback capacitance	$I_C = 0$ ; $V_{CB} = -10\text{ V}$ ; $f = 1\text{ MHz}$	–	0.5	–	pF
$f_T$	transition frequency	$I_C = -15\text{ mA}$ ; $V_{CE} = -10\text{ V}$ ; $f = 500\text{ MHz}$	–	4	–	GHz
$G_{UM}$	maximum unilateral power gain	$I_C = -15\text{ mA}$ ; $V_{CE} = -10\text{ V}$ ; $f = 500\text{ MHz}$ ; $T_{amb} = 25\text{ }^\circ\text{C}$	–	17	–	dB
F	noise figure	$I_C = -5\text{ mA}$ ; $V_{CE} = -10\text{ V}$ ; $f = 500\text{ MHz}$	–	2.5	–	dB
$T_j$	junction temperature		–	–	150	$^\circ\text{C}$

### Note

1.  $T_s$  is the temperature at the soldering point of the collector pin.

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**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CB0</sub>	collector-base voltage	open emitter	–	–20	V
V <sub>CEO</sub>	collector-emitter voltage	open base	–	–15	V
V <sub>EBO</sub>	emitter-base voltage	open collector	–	–2	V
I <sub>C</sub>	collector current (DC)		–	–25	mA
P <sub>tot</sub>	total power dissipation	up to T <sub>s</sub> = 93 °C; note 1	–	300	mW
T <sub>stg</sub>	storage temperature		–65	+150	°C
T <sub>j</sub>	junction temperature		–	150	°C

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-s</sub>	thermal resistance from junction to soldering point	up to T <sub>s</sub> = 93 °C; note 1	190	K/W

**Note to the “Limiting values” and “Thermal characteristics”**

1. T<sub>s</sub> is the temperature at the soldering point of the collector pin.

**CHARACTERISTICS**T<sub>j</sub> = 25 °C (unless otherwise specified).

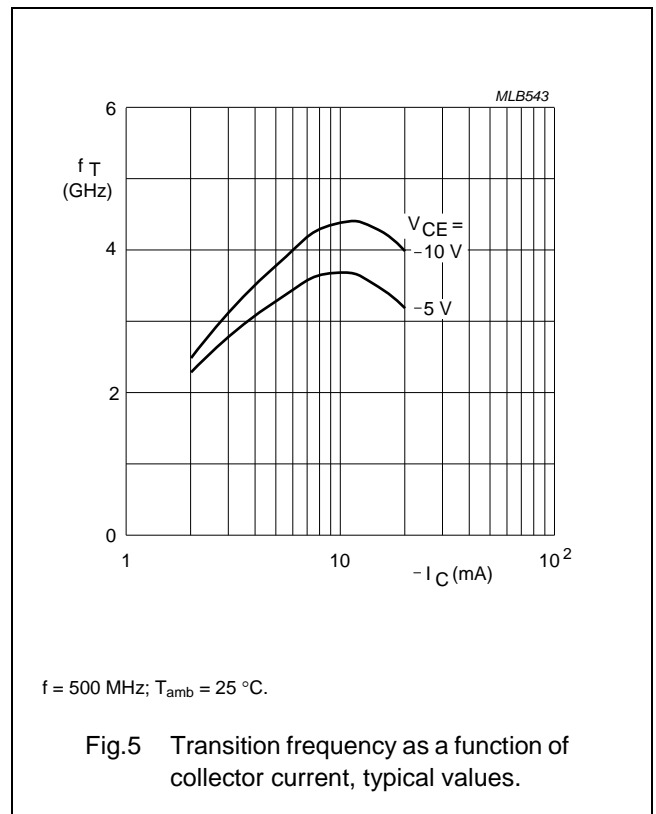
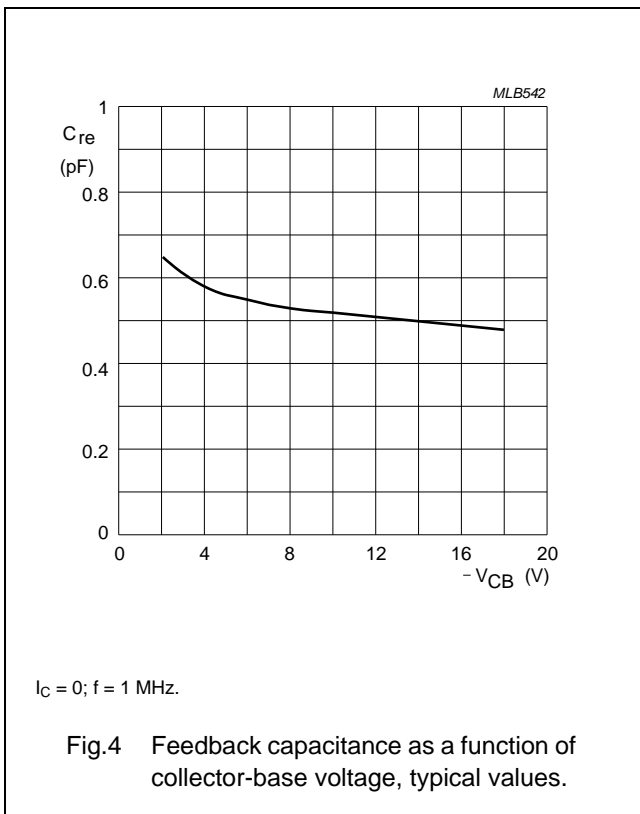
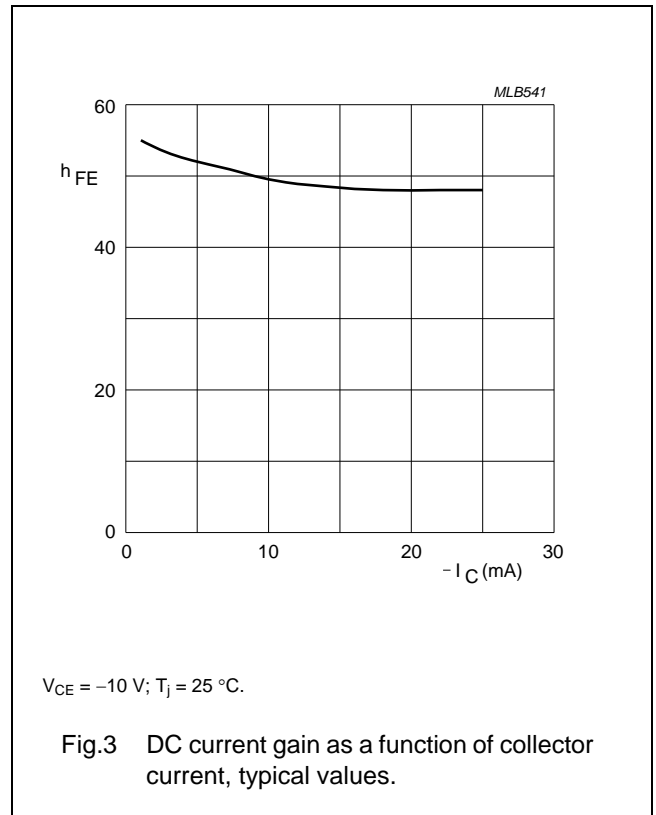
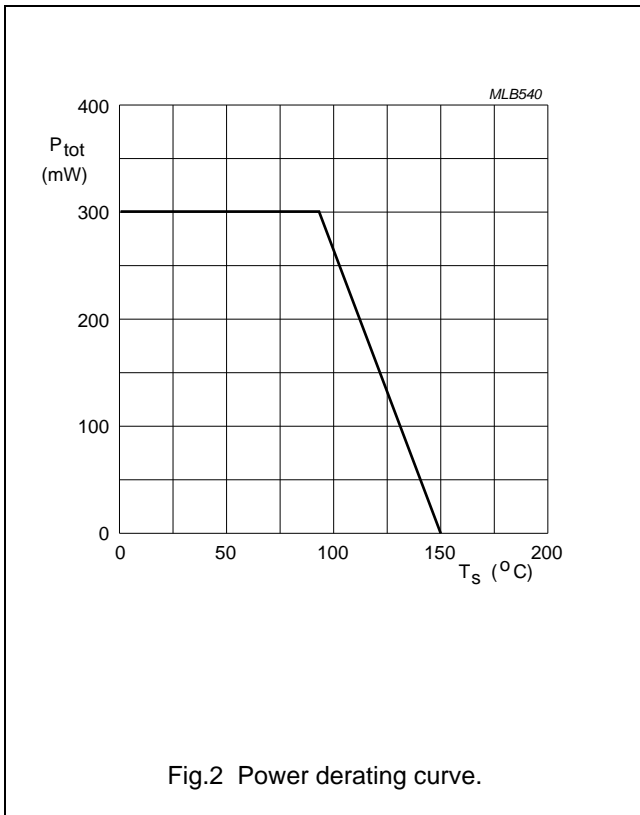
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector cut-off current	I <sub>E</sub> = 0; V <sub>CB</sub> = –10 V	–	–	–50	nA
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = –15 mA; V <sub>CE</sub> = –10 V	20	50	–	
f <sub>T</sub>	transition frequency	I <sub>C</sub> = –15 mA; V <sub>CE</sub> = –10 V; f = 500 MHz; T <sub>amb</sub> = 25 °C	–	4	–	GHz
C <sub>c</sub>	collector capacitance	I <sub>E</sub> = i <sub>e</sub> = 0; V <sub>CB</sub> = –10 V; f = 1 MHz	–	0.65	–	pF
C <sub>e</sub>	emitter capacitance	I <sub>C</sub> = i <sub>c</sub> = 0; V <sub>EB</sub> = –0.5 V; f = 1 MHz	–	0.75	–	pF
C <sub>re</sub>	feedback capacitance	I <sub>C</sub> = 0; V <sub>CB</sub> = –10 V; f = 1 MHz	–	0.5	–	pF
G <sub>UM</sub>	maximum unilateral power gain; note 1	I <sub>C</sub> = –15 mA; V <sub>CE</sub> = –10 V; f = 500 MHz; T <sub>amb</sub> = 25 °C	–	17	–	dB
		I <sub>C</sub> = –15 mA; V <sub>CE</sub> = –10 V; f = 1 GHz; T <sub>amb</sub> = 25 °C	–	11	–	dB
F	noise figure	Γ <sub>s</sub> = Γ <sub>opt</sub> ; I <sub>C</sub> = –5 mA; V <sub>CE</sub> = –10 V; f = 500 MHz	–	2.5	–	dB
		Γ <sub>s</sub> = Γ <sub>opt</sub> ; I <sub>C</sub> = –5 mA; V <sub>CE</sub> = –10 V; f = 1 GHz	–	3	–	dB

**Note**

1. G<sub>UM</sub> is the maximum unilateral power gain, assuming s<sub>12</sub> is zero.  $G_{UM} = 10 \log \frac{|s_{21}|^2}{(1 - |s_{11}|^2)(1 - |s_{22}|^2)}$  dB.

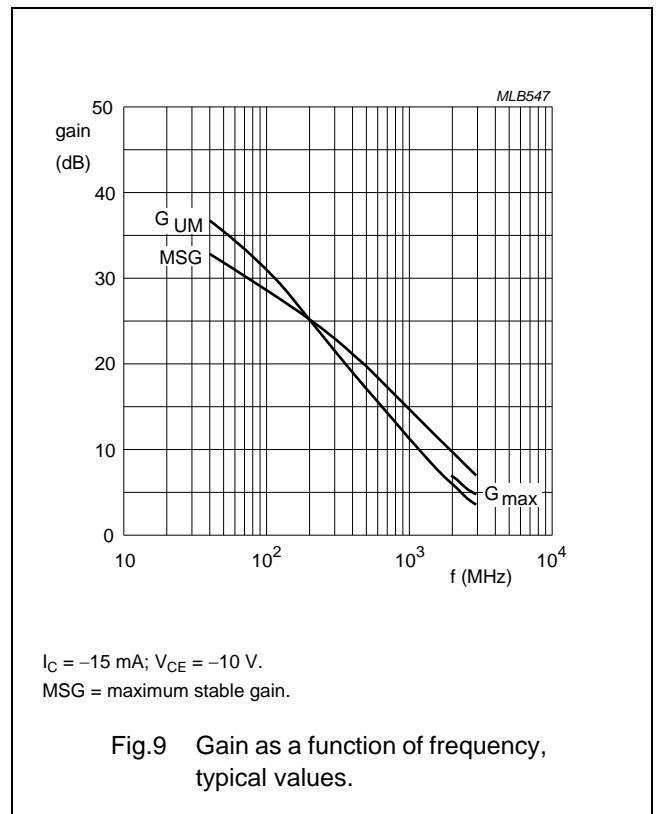
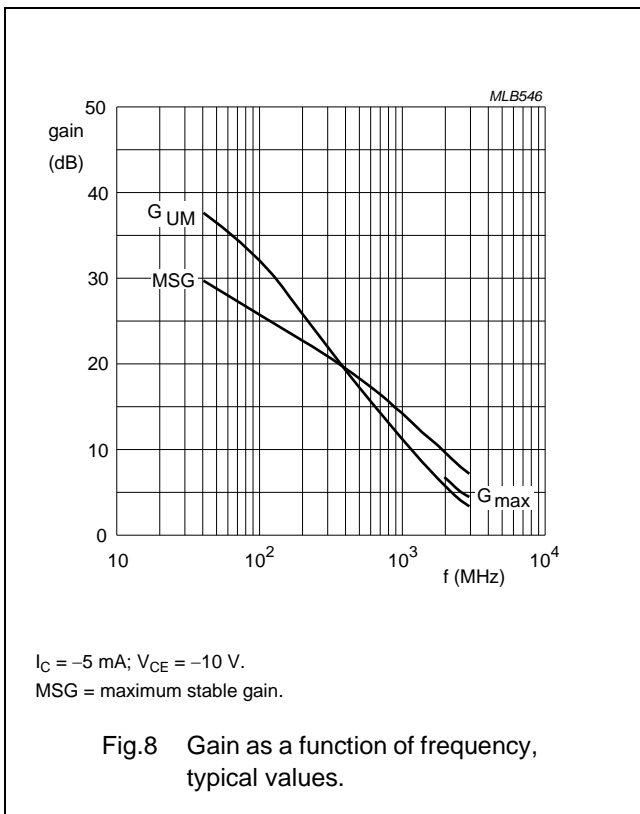
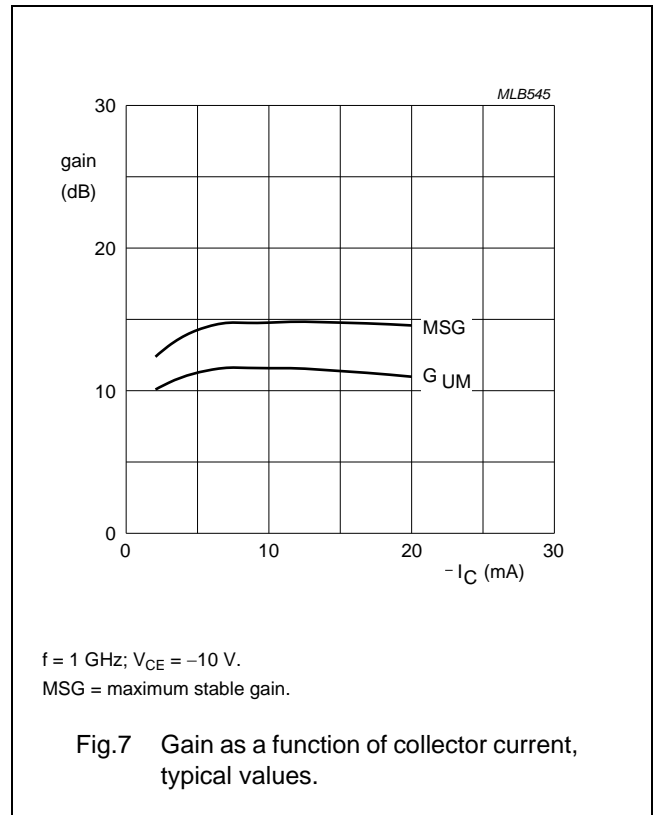
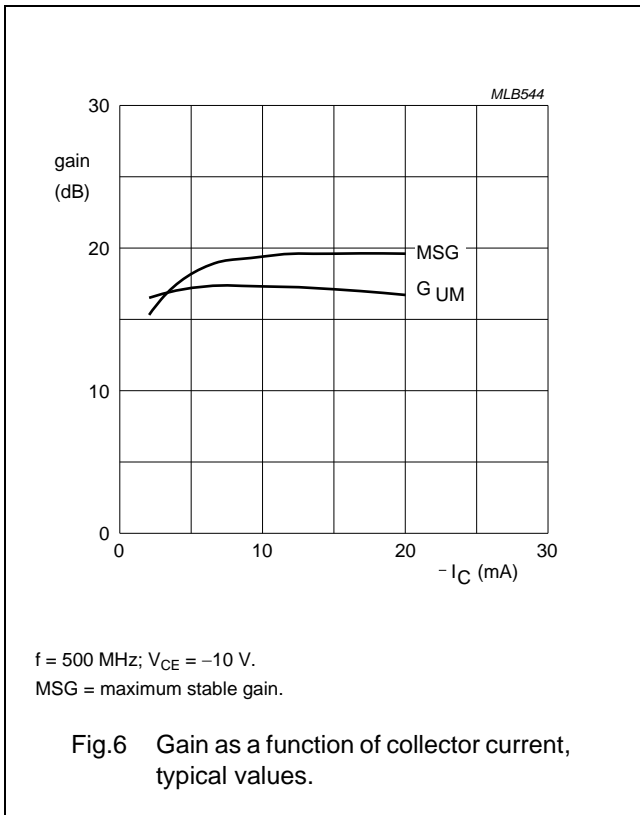
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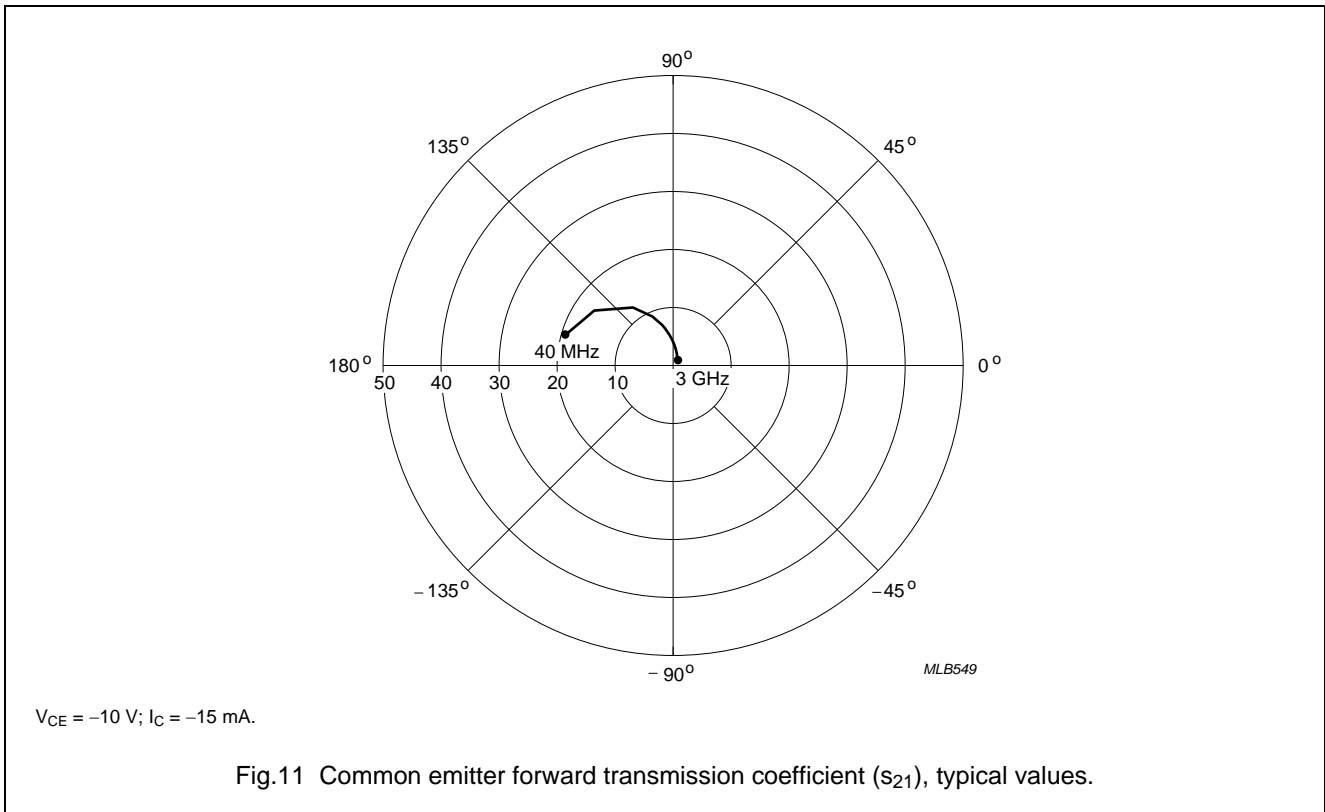
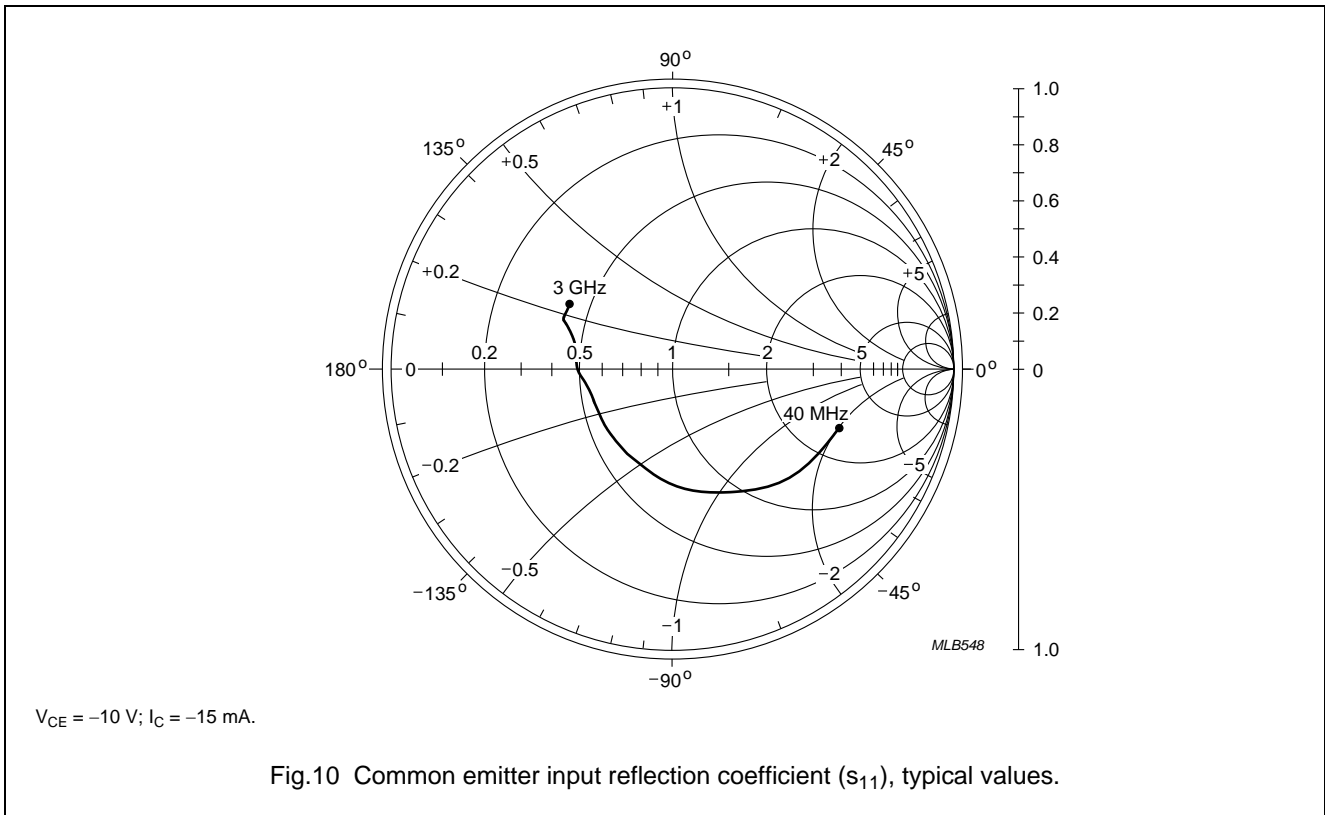
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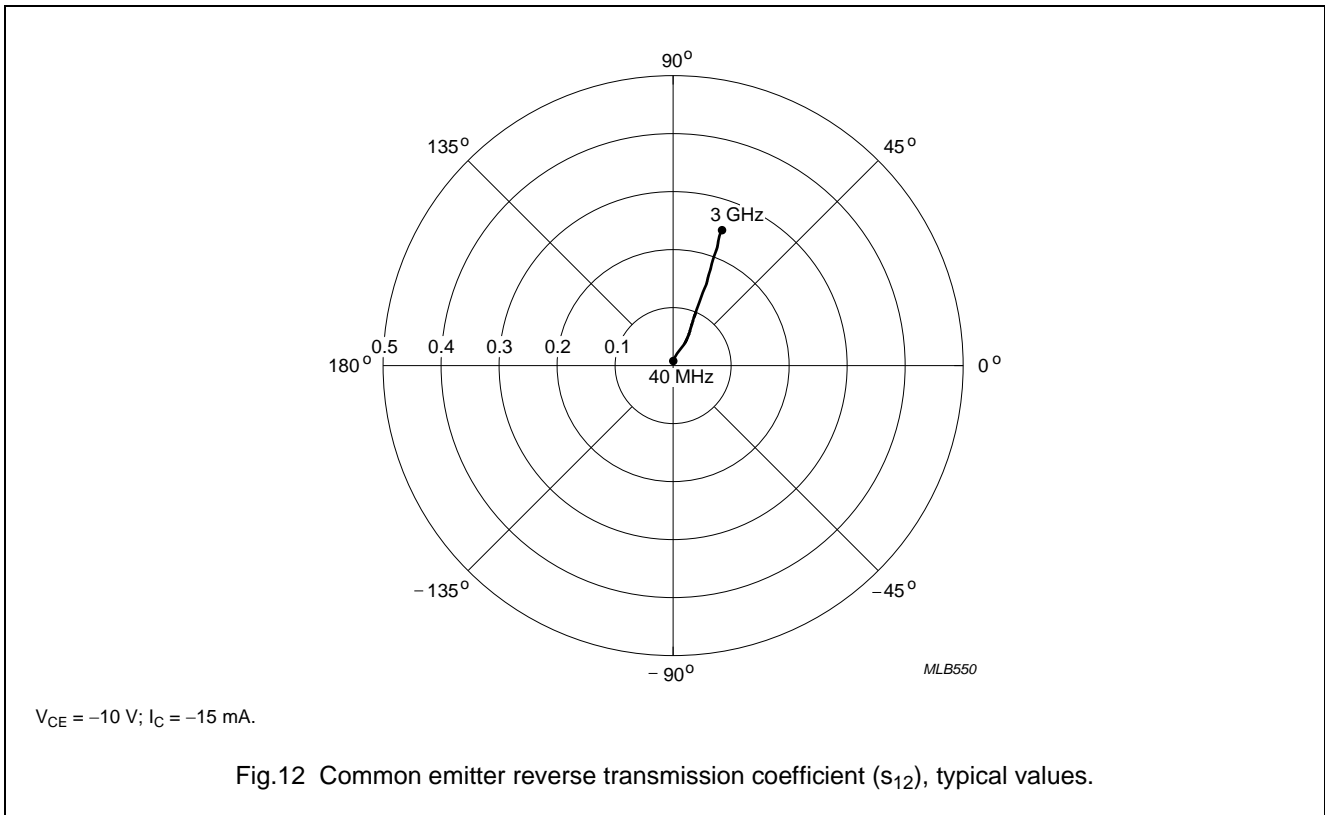


Fig.12 Common emitter reverse transmission coefficient ( $s_{12}$ ), typical values.

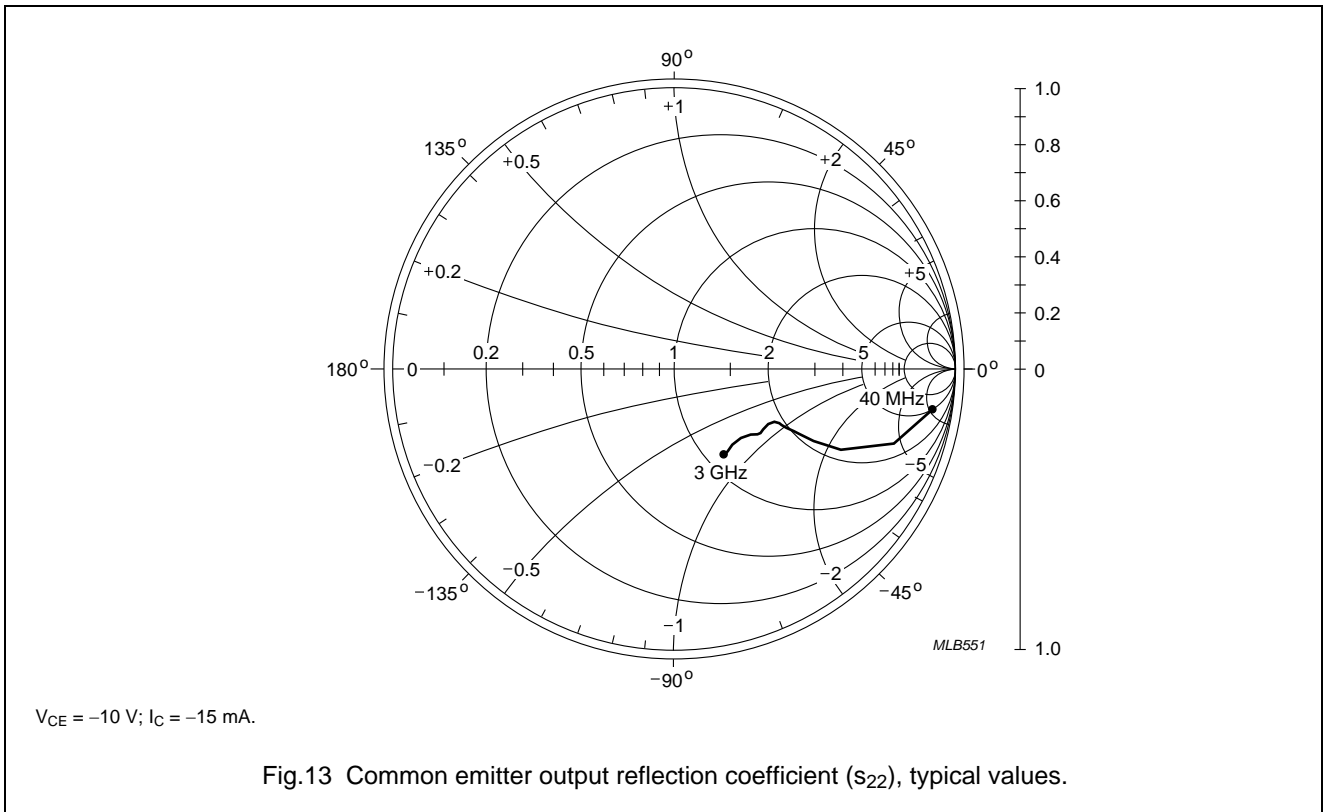
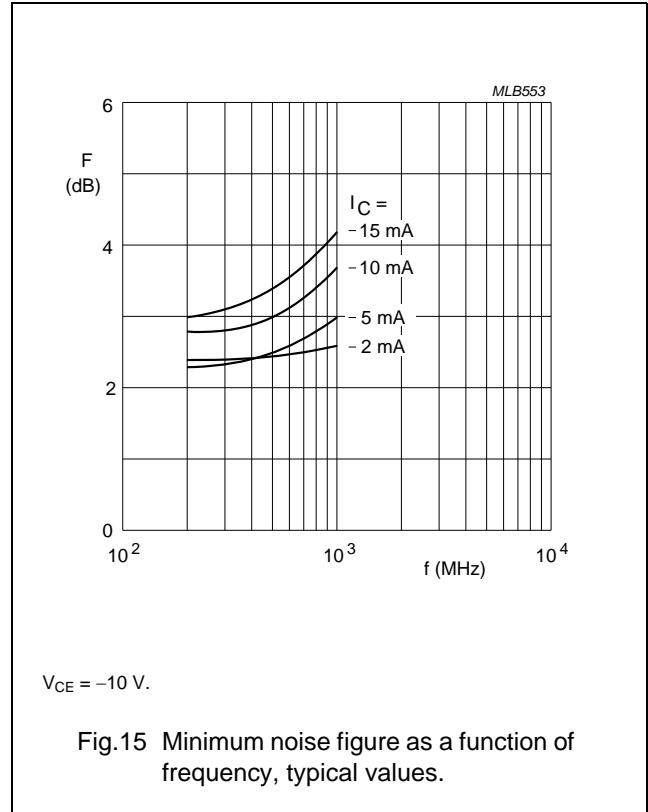
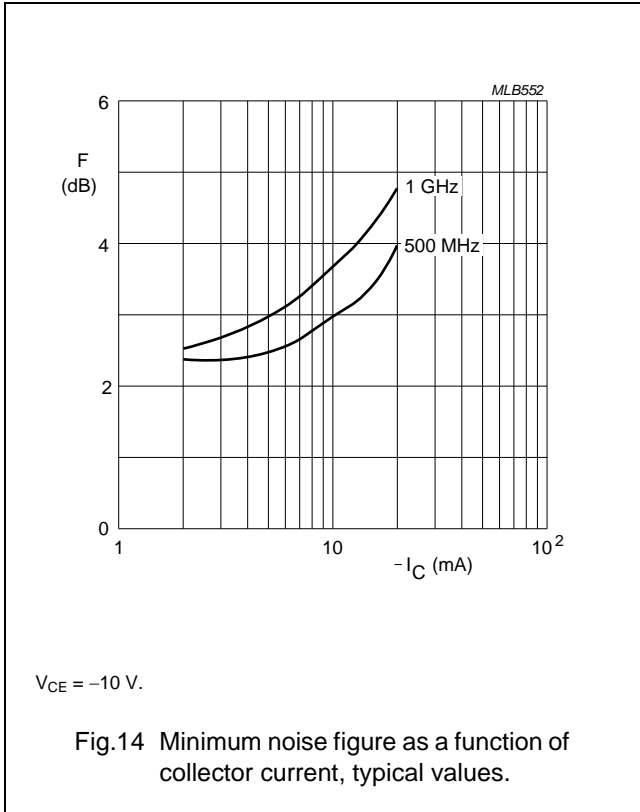


Fig.13 Common emitter output reflection coefficient ( $s_{22}$ ), typical values.

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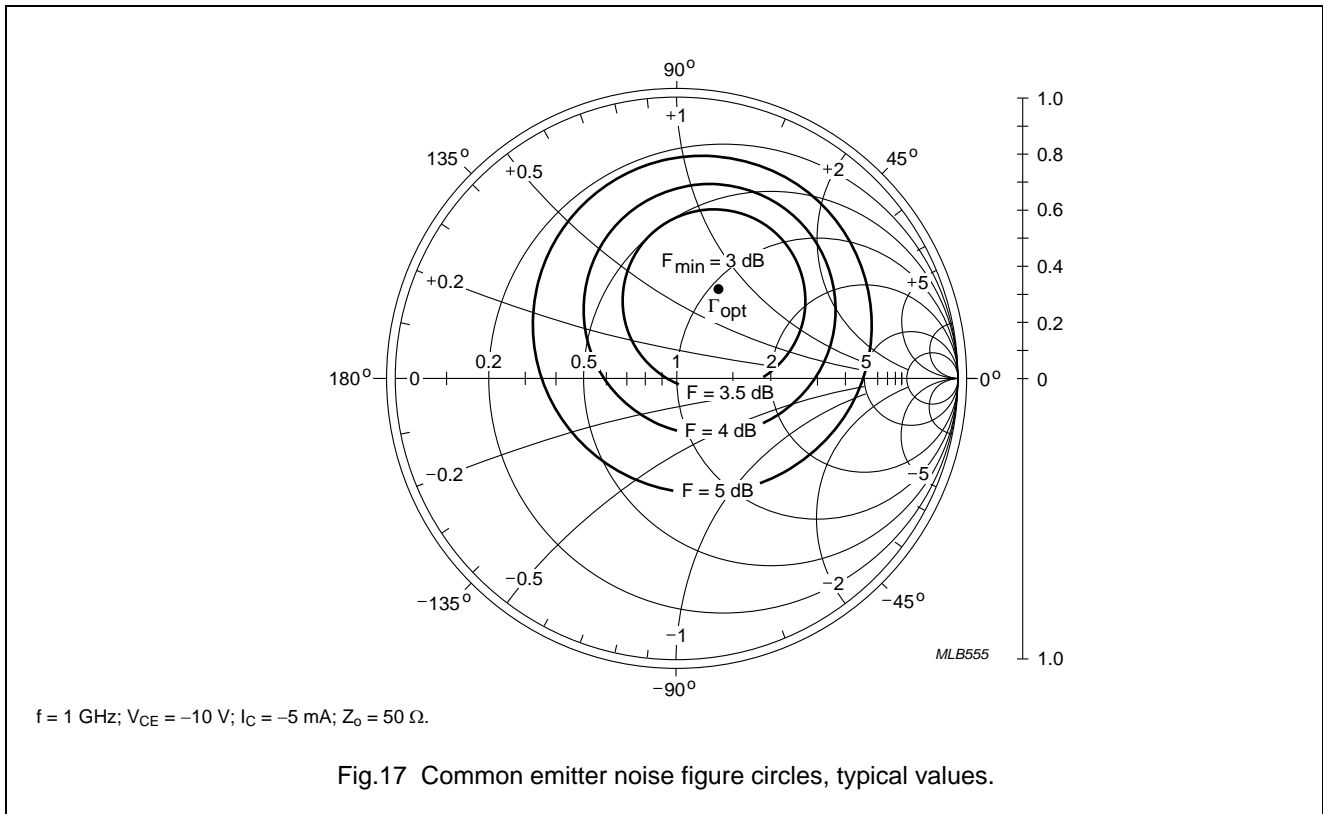
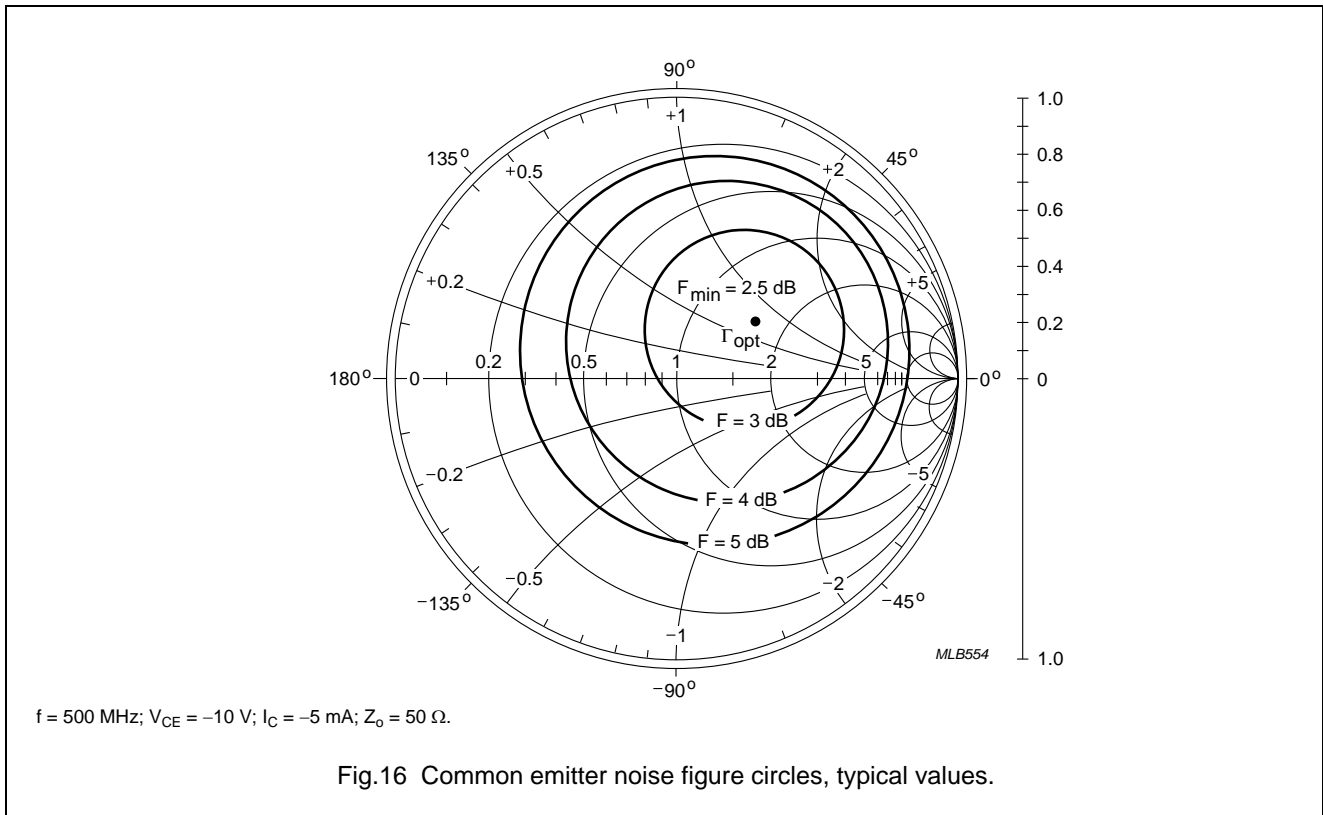
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SPICE parameters for the BFT92W crystal

SEQUENCE No.	PARAMETER	VALUE	UNIT
1	IS	437.5	aA
2	BF	33.58	–
3	NF	1.009	–
4	VAF	23.39	V
5	IKF	99.53	mA
6	ISE	87.05	fA
7	NE	1.943	–
8	BR	4.947	–
9	NR	1.002	–
10	VAR	3.903	V
11	IKR	5.281	mA
12	ISC	35.88	fA
13	NC	1.393	–
14	RB	5.000	Ω
15	IRB	1.000	μA
16	RBM	5.000	Ω
17	RE	1.000	Ω
18	RC	10.00	Ω
19 <sup>(1)</sup>	XTB	0.000	–
20 <sup>(1)</sup>	EG	1.110	eV
21 <sup>(1)</sup>	XTI	3.000	–
22	CJE	746.6	fF
23	VJE	600.0	mV
24	MJE	0.357	–
25	TF	17.49	ps
26	XTF	1.354	–
27	VTF	155.6	mV
28	ITF	1.000	mA
29	PTF	45.00	deg
30	CJC	937.1	fF
31	VJC	396.4	mV
32	MJC	0.200	–
33	XCJC	0.106	–
34	TR	8.422	ns
35 <sup>(1)</sup>	CJS	0.000	F

SEQUENCE No.	PARAMETER	VALUE	UNIT
36 <sup>(1)</sup>	VJS	750.0	mV
37 <sup>(1)</sup>	MJS	0.000	–
38	FC	0.768	–

Note

1. These parameters have not been extracted, the default values are shown.

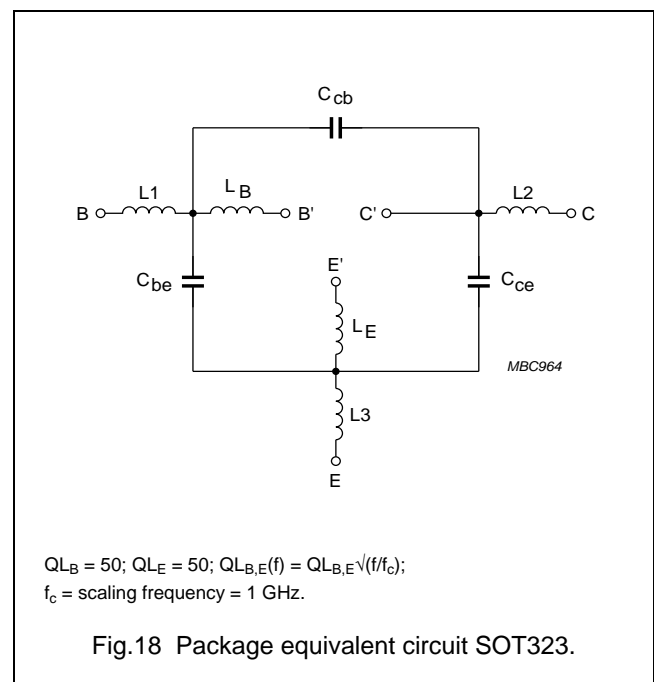


Fig.18 Package equivalent circuit SOT323.

List of components (see Fig.18)

DESIGNATION	VALUE	UNIT
$C_{be}$	2	fF
$C_{cb}$	100	fF
$C_{ce}$	100	fF
L1	0.34	nH
L2	0.10	nH
L3	0.34	nH
$L_B$	0.60	nH
$L_E$	0.60	nH

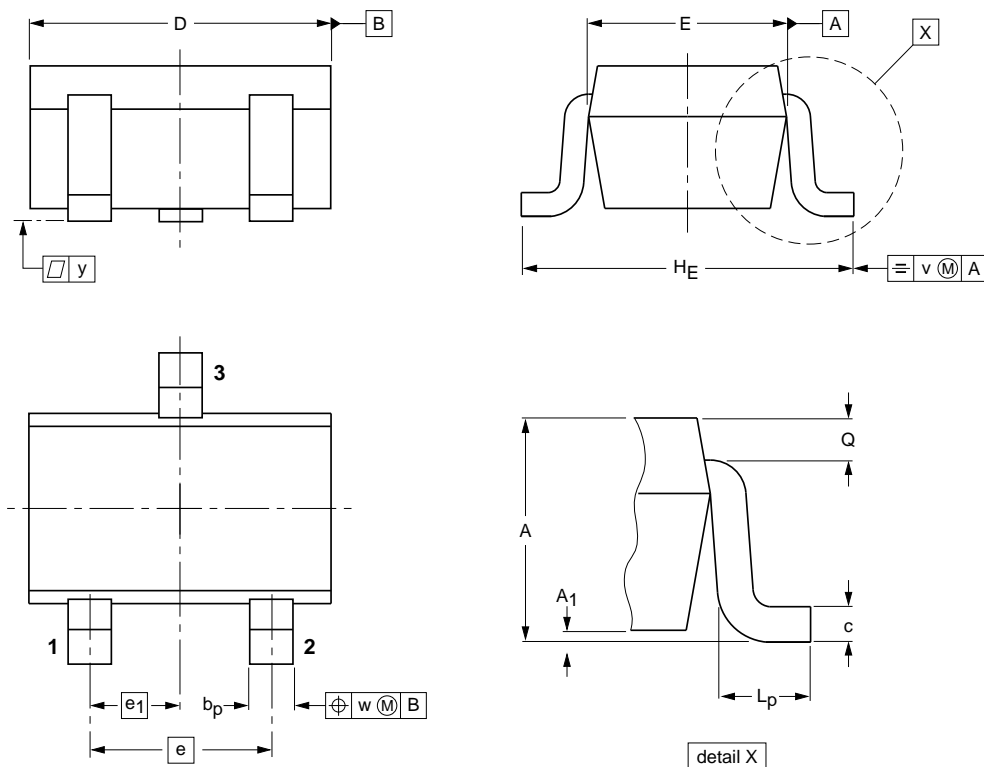
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PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads

SOT323



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	b <sub>p</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT323			SC-70			04-11-04 06-03-16

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## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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## **Contact information**

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